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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shunpei Yamazaki	05/08/2001
Jun Koyama	05/08/2001

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.	
Street Address:	398, HASE	
City:	ATSUGI-SHI, KANAGAWA-KEN	
State/Country:	JAPAN	
Postal Code:	243-0036	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14257097

CORRESPONDENCE DATA

Fax Number: (877)769-7945

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (202) 783-5070 Email: apsi@fr.com

Correspondent Name: JOHN F. HAYDEN

Address Line 1: FISH & RICHARDSON P.C.

Address Line 2: P.O.BOX 1022

Address Line 4: MINNEAPOLIS, MINNESOTA 55440-1022

ATTORNEY DOCKET NUMBER: 12732-0012007 NAME OF SUBMITTER: APRIL K. SAUNDERS-FULLER SIGNATURE: /April K. Saunders-Fuller/ **DATE SIGNED:** 05/28/2014

Total Attachments: 1

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PATENT REEL: 032979 FRAME: 0097 502827459

Attorney Docket No. 12732-0012007 Client Reference No. US04638D1-C1C1C1C1

ASSIGNMENT

For valuable consideration, We, Shunpei YAMAZAKI of Setagaya, Tokyo, Japan and Jun KOYAMA of Sagamihara, Kanagawa, Japan, hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled <u>SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME</u> filed 04/21/2014 and assigned U.S. Serial Number 14257097 and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature:

Name:

Shumpei YAMAZAKI

Date:

05/08/2001

Signature:

RECORDED: 05/28/2014

un KOYAMA

Name: Date:

n5/n8/200/

PATENT REEL: 032979 FRAME: 0098